

RF PRODUCT INFORMATION

Multi Layer Chip Diplexer – 2012 (0805)

- ISM Band 2.4GHz & 5GHz
- RFDIP2012100L1T

For WLAN 802.11b/g/a Combo Application

Patent Pending



FEATURES

1. LTCC (Low Temperature Cofired Ceramics) Technology
2. Miniatured Size 2.00 x 1.25 x 1.00 mm³
3. Low Insertion Loss reduces power consumption
4. High Isolation
5. High band wide bandwidth design covers from 4.9GHz to 6.0GHz

ELECTRICAL CHARACTERISTICS

RFDIP2012100L0T	Band_1	Band_2
Central Frequency	2450 ± 50 MHz	5400 ± 500 MHz
Impedance	50 Ω	50 Ω
Insertion Loss	0.7dB	0.9dB
Return Loss	Min. 10 dB	
Attenuation	-20dB @ 4.9GHz -20dB @ 5.2GHz -20dB @ 5.8GHz	-20dB @ 2.45GHz
Ripple	0.5dB	

APPLICATIONS

- ISM Band 2.4GHz/ 5GHz WLAN 802.11b/g/a Combo Applications.
- Band-switching for dual-band system.

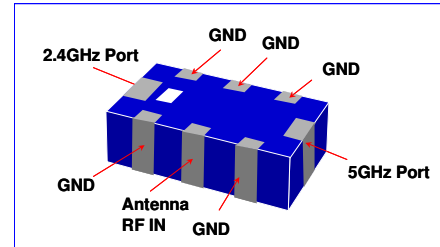
DIMENSION

Figure	Symbol	Dimension
	L	2.00 ± 0.15 mm
	W	1.25 ± 0.15 mm
	t	0.95 ± 0.10 mm
	a	0.20 ± 0.20 mm
	b	0.30 ± 0.20 mm
	c	0.35 ± 0.20 mm
	d	0.65 ± 0.20 mm
	e	0.30 ± 0.20 mm
	f	0.25 ± 0.20 mm

SOLDER LAND PATTERN

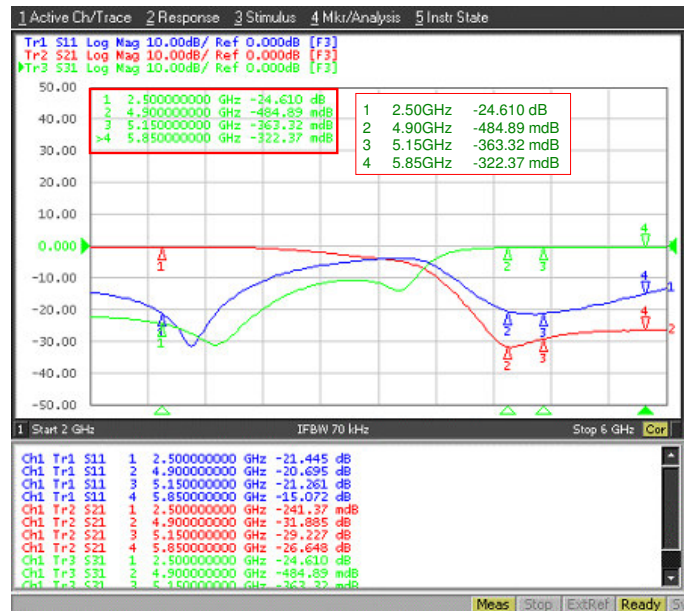
	Line width to be design to match 50Ω characteristic impedance, depending on PCB material and thickness
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CONSTRUCTION



Outline of 2.4GHz/ 5GHz Diplexer (2012 size)

ELECTRICAL PERFORMANCE



CONTACT INFORMATION

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Specification subject to change without prior notice.